

DRIVE INNOVATION • DELIVER EXCELLENCE >



ASMI ANNUAL MEETING OF SHAREHOLDERS

Chuck del Prado, President & CEO
May 16 2013

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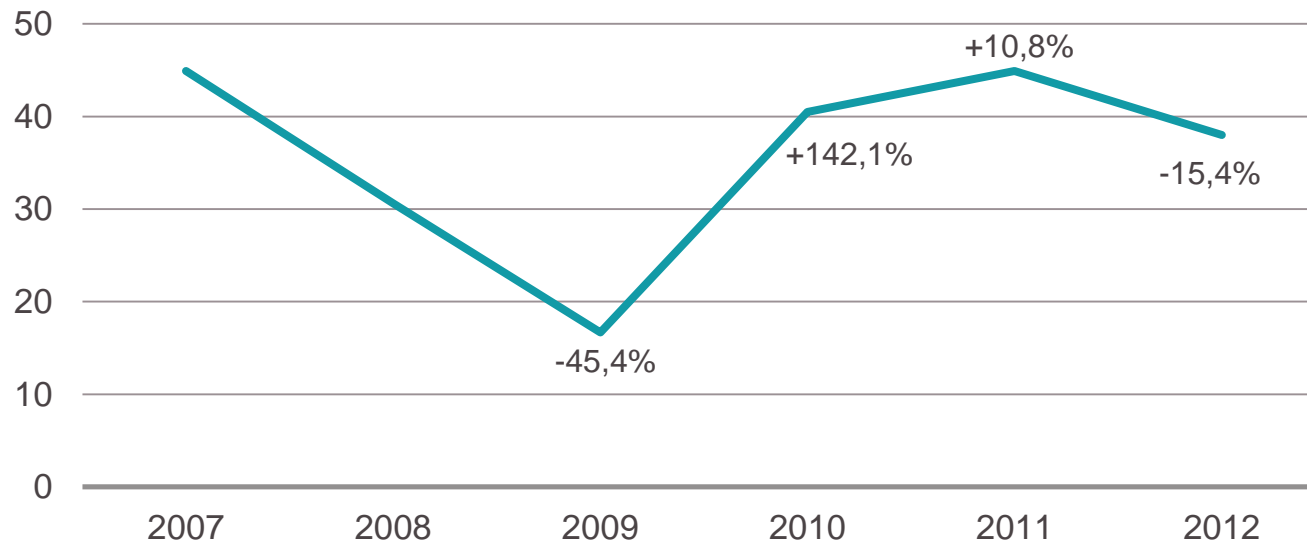
OUTLINE

- › **Semiconductor Equipment Market in 2012**
- › ASMI Results in 2012
- › Status ASMI Back-end
 - Results
 - Products & Business highlights
- › Status ASMI Front-end
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 - Products & Business highlights
- › Market Outlook and Conclusions

OUR INDUSTRY TURNED DOWN IN 2012

Semi Capital Equipment

(USD billion)

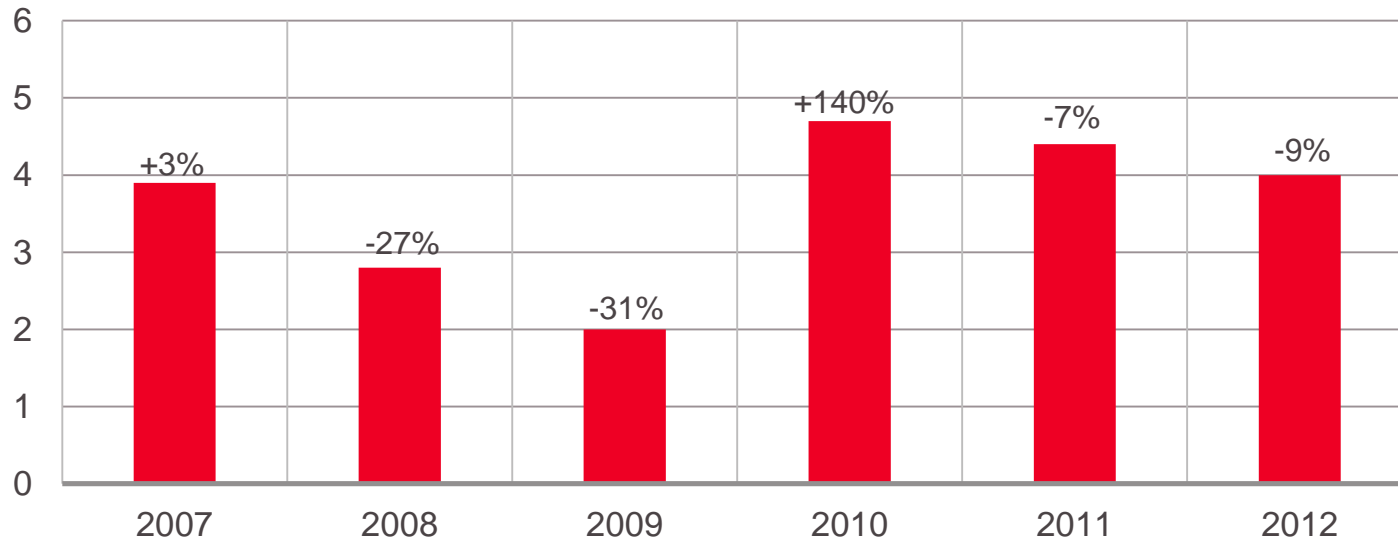


After 2 years of growth, our industry declined in 2012

Source: Gartner, March 2013

Assembly & Packaging equipment market 2012

(USD billion)

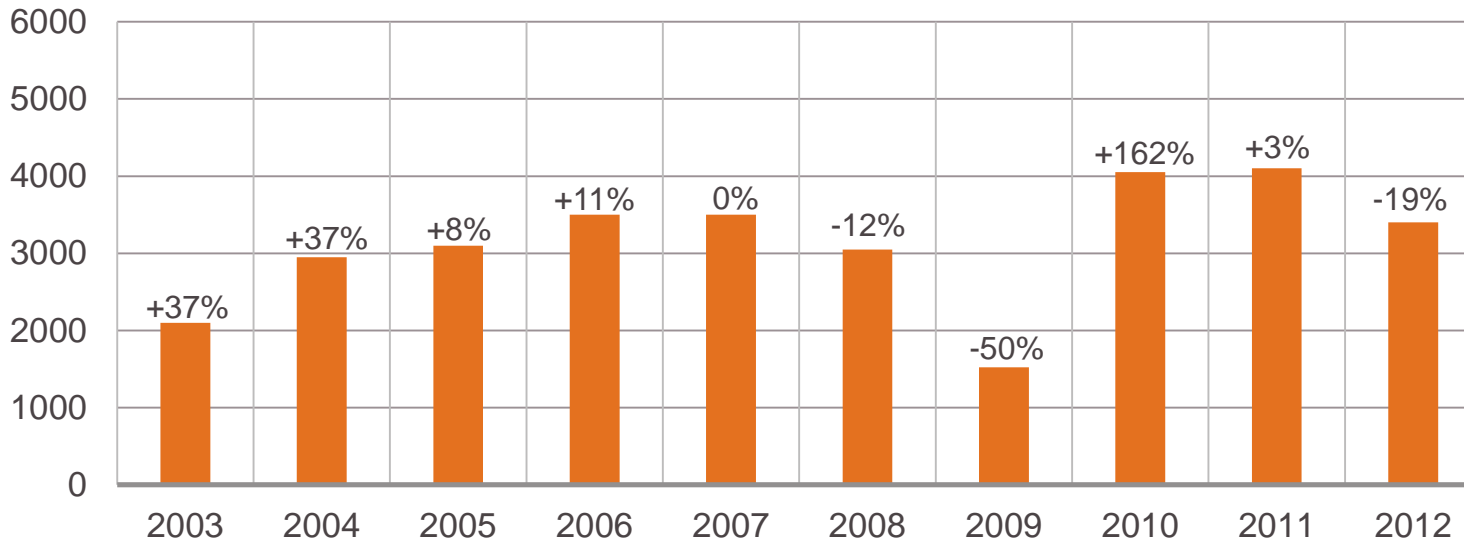


Assembly & Packaging equipment spending declined in 2012

Source: Gartner, March 2013

SMT* equipment market 2012

(USD million)



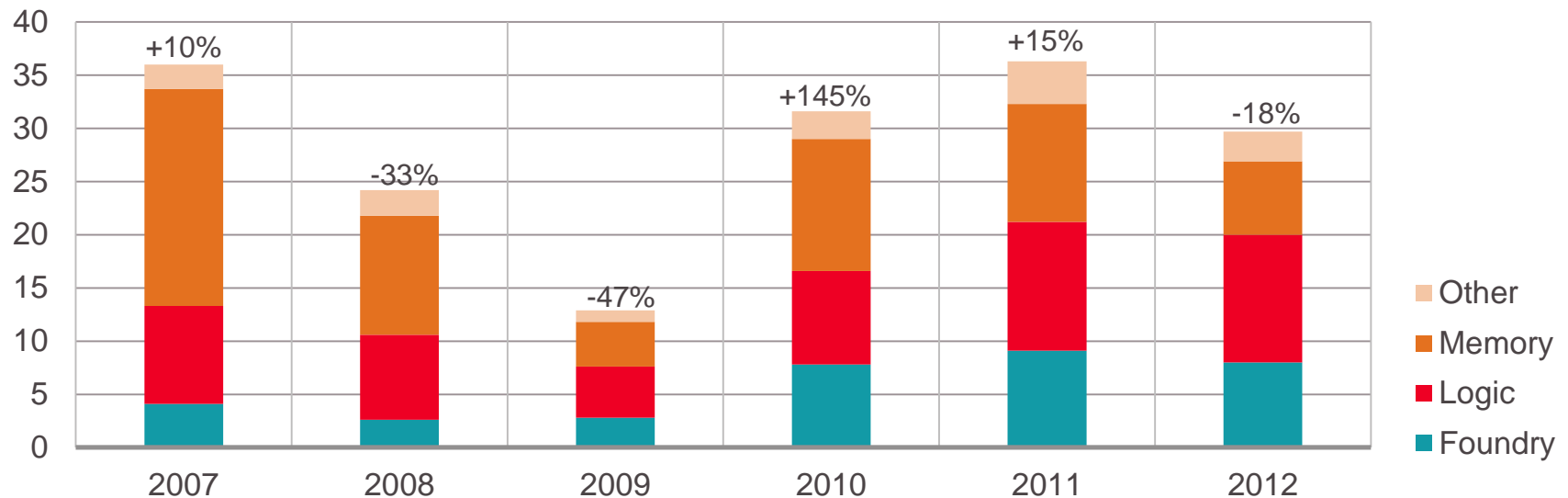
SMT equipment market was down in 2012

Source: ASM SIPLACE market intelligence, February 2013

*SMT = Surface Mount Technology

Wafer Fab Equipment by device type

(USD billion)



- > 2012 WFE spending decreased by 18%
- > Logic & Foundry declined slightly in 2012
- > Memory declined substantially

Source: Gartner, March 2013

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› **Revenues down 13% y-o-y**

- FE sales decreased 19% y-o-y
- BE sales decreased 11% y-o-y

› **EBIT margin of 6%**

- FE EBIT margin down from 14% in 2011 to 0.4% in 2012
- BE EBIT margin down from 18% in 2011 to 8% in 2012

› **Cash flow from operations of €42m in 2012**

- Proposal to ASMI AGM for dividend of €0.50 per share

› **Net earnings of €7m down from €187m in 2011**

- 2011 included gain on bargain purchase of €51m

NET EARNINGS – GROUP



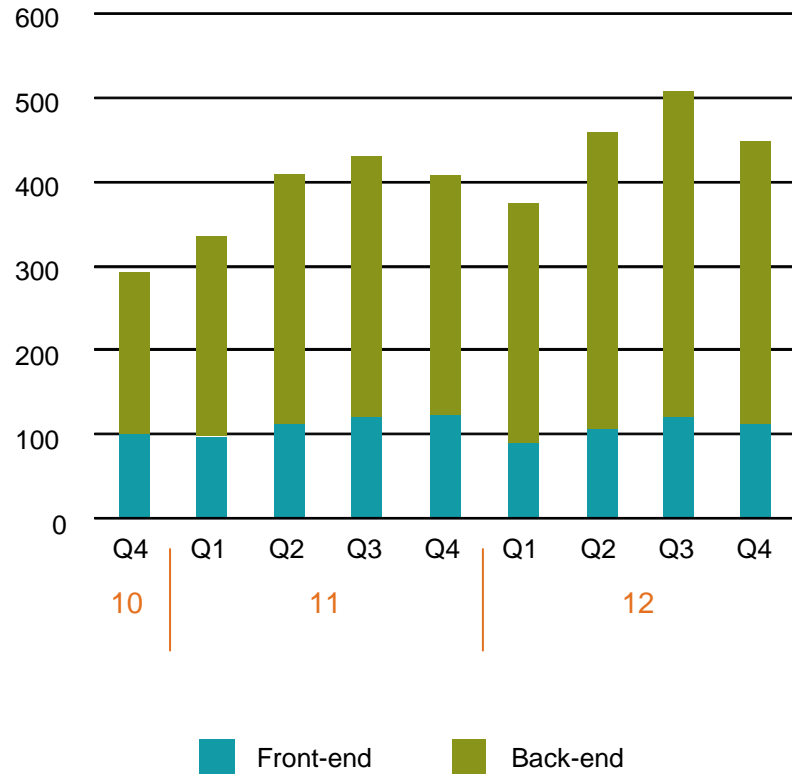
(EUR million)	FULL YEAR 2011	FULL YEAR 2012	Q1 2012	Q2 2012	Q3 2012	Q4 2012	Q1 2013
Front-end	456.1	370.4	94.8	86.5	96.1	93.1	80.0
Back-end	1,178.3	1,047.7	216.3	291.4	313.2	226.8	160.3
NET SALES	1,634.3	1,418.1	311,1	377.9	409.3	319.9	240.3
Front-end	37.8%	33.6%	33.0%	33.0%	31.4%	37.1%	37.7%
Back-end	34.8%	30.2%	30.2%	35.0%	30.4%	23.5%	24.0%
GROSS MARGIN	582.2	440.4	96.6	130.6	125.4	87.8	68.6
as % of sales	35.6%	31.1%	31.1%	34.6%	30.6%	27.4%	28.5%
Selling, general and administrative	(176.5)	(202.1)	(41.2)	(53.8)	(53.6)	(53.5)	(40.9)
Research and development	(129.4)	(149.2)	(33.5)	(38.2)	(40.0)	(37.5)	(30.5)
Front-end	62.6	1.4	2.9	(1.9)	(1.6)	2.1	1.4
Back-end (100%)	213.7	87.7	19.0	40.5	33.6	(5.3)	(4.3)
EBIT (excl. restructuring/impairment)	276.3	89.2	21.9	38.5	31.9	(3.2)	(2.9)
as % of sales	16.9%	6.3%	7.1%	10.2%	7.8%	-1.0%	-1.2%
Restructuring	-	(0.9)	-	-	-	(0.9)	(0.3)
Bargain purchase (PPA)	97.8	-	-	-	-	-	-
Impairment	(8.0)	-	-	-	-	-	-
Front-end	44.5	(29.1)	(2.5)	1.3	(8.4)	(19.5)	3.1
Back-end (ASMI interest)	142.2	36.4	8.8	16,5	13.3	(2.2)	(0.5)
Gain on sale shares	-	-	-	-	-	-	1,407.6
NET RESULT	186.8	7.1	6.2	17.7	4.9	(21.7)	1,410.1

BALANCE SHEET – GROUP

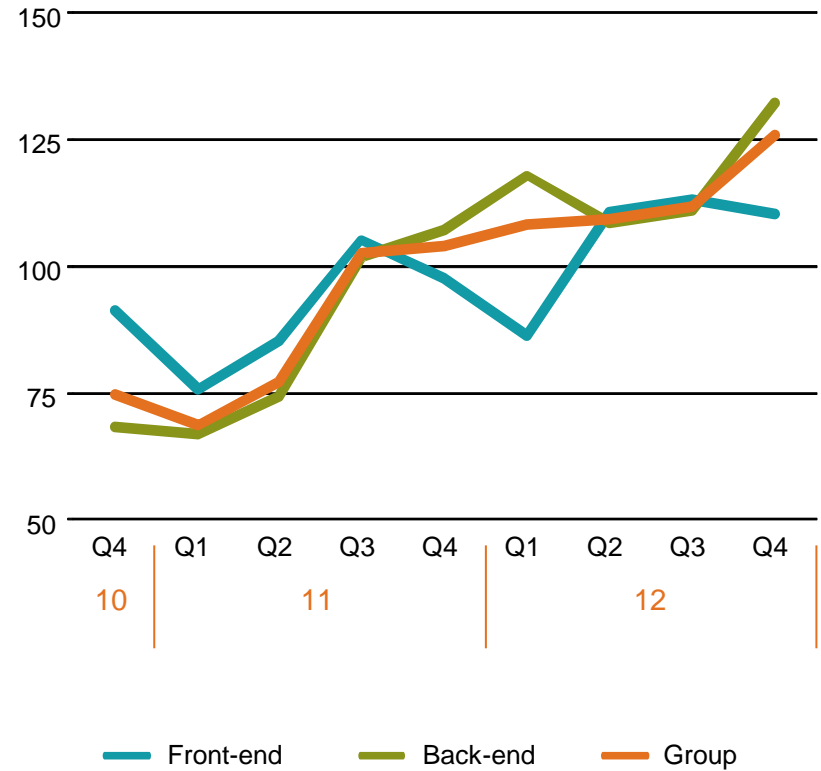
(EUR million)	DEC 2011	MAR 2012	JUN 2012	SEP 2012	DEC 2012	MAR 2013
Cash and cash equivalents	390	405	334	297	291	565
Other current assets	806	773	917	901	804	208
Property, plant and equipment, net	260	259	279	275	275	61
Goodwill, net	52	51	54	52	52	12
Other assets	74	74	84	89	75	1,381
TOTAL ASSETS	1,582	1,561	1,668	1,615	1,496	2,226
ST debt (incl. current LT debt)	45	40	72	86	68	-
Other current liabilities	418	409	449	390	344	86
Long-term debt & convertible subordinated debt	150	150	152	144	13	-
Other long term liabilities	11	11	17	17	21	4
TOTAL LIABILITIES	625	610	690	637	446	90
Total shareholders' equity	660	653	665	667	742	2,136
Non-controlling interest	298	298	313	311	308	-
TOTAL LIABILITIES AND EQUITY	1,582	1,561	1,668	1,615	1,496	2,226

WORKING CAPITAL – GROUP

(EUR in million)



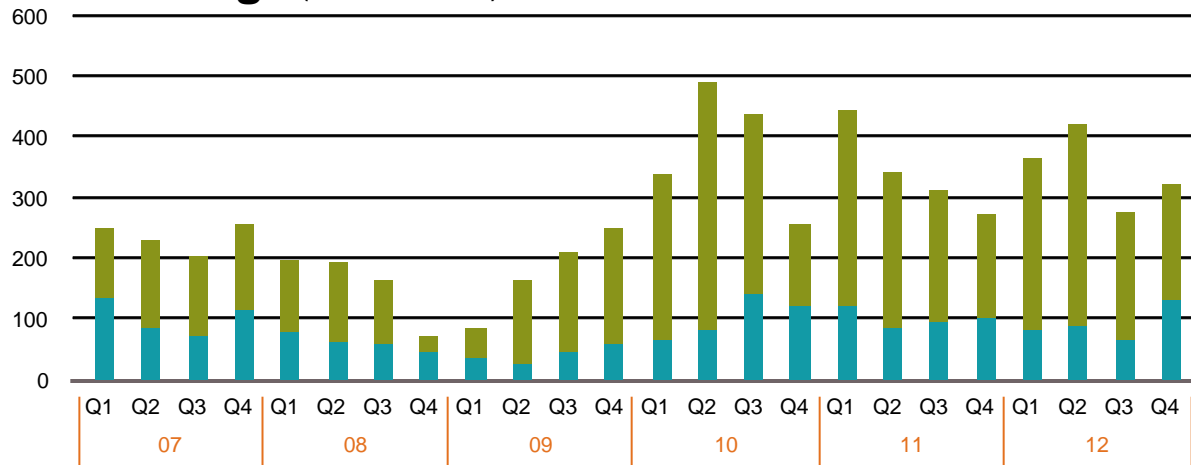
Days



CASH FLOW – GROUP

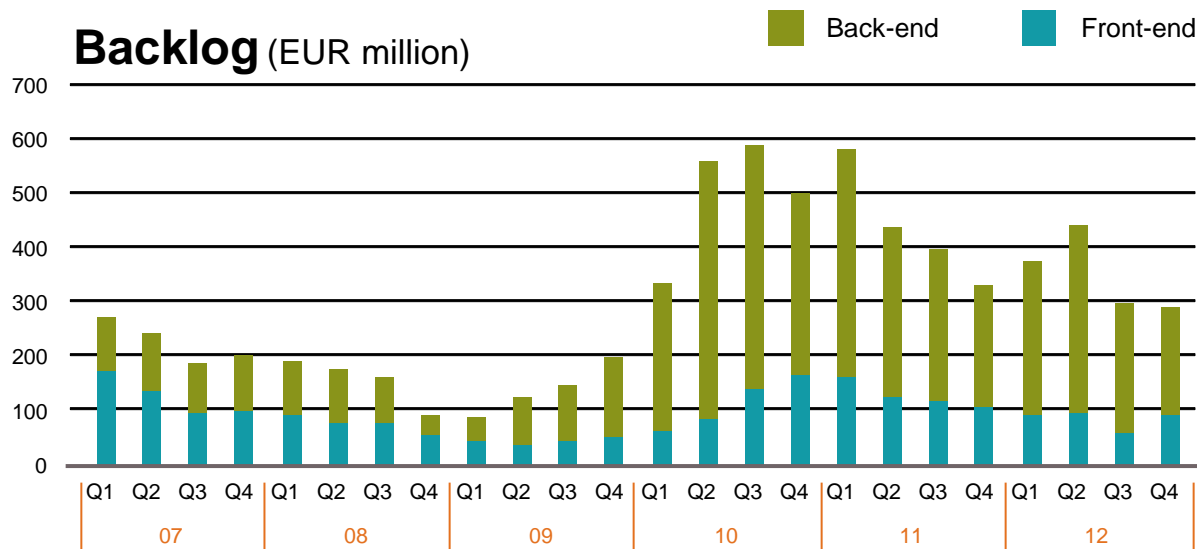
(EUR million)	FULL YEAR 2011	FULL YEAR 2012	Q1 2012	Q2 2012	Q3 2012	Q4 2012
Net result	316.2	40.4	14.2	32.8	17.2	(23.8)
Depreciation	49.5	56.9	13.1	13.7	15.1	15.0
Working capital	(39.2)	(60.8)	19.3	(62.2)	(59.7)	41.8
Restructuring & impairments	4.9	0.1	0.1	-	-	-
Others	(114.7)	5.9	(7.3)	(11.6)	7.7	17.1
Net cash from operating activities	216.6	42.5	40.2	(27.2)	(19.8)	50.1
Net cash from investing activities	(93.4)	(71.9)	(18.4)	(17.8)	(14.5)	(21.1)
Net cash from financing activities	(45.4)	(73.5)	(5.8)	(27.4)	(5.2)	(35.1)
Exchange rate effects	(7.8)	3.1	(0.8)	1.5	3.2	(0.8)
NET INCREASE (DECREASE) IN CASH AND CASH EQUIVALENTS	70.0	(99.8)	14.4	(70.9)	(36.4)	(6.8)

Bookings (EUR million)



Book to bill ratio in 2012 of 1.0 (2011 was 0.8)

Backlog (EUR million)



Backlog decreased from €331m at the end of 2011, to €289m at the end of 2012

USE OF ASMPT DIVIDENDS

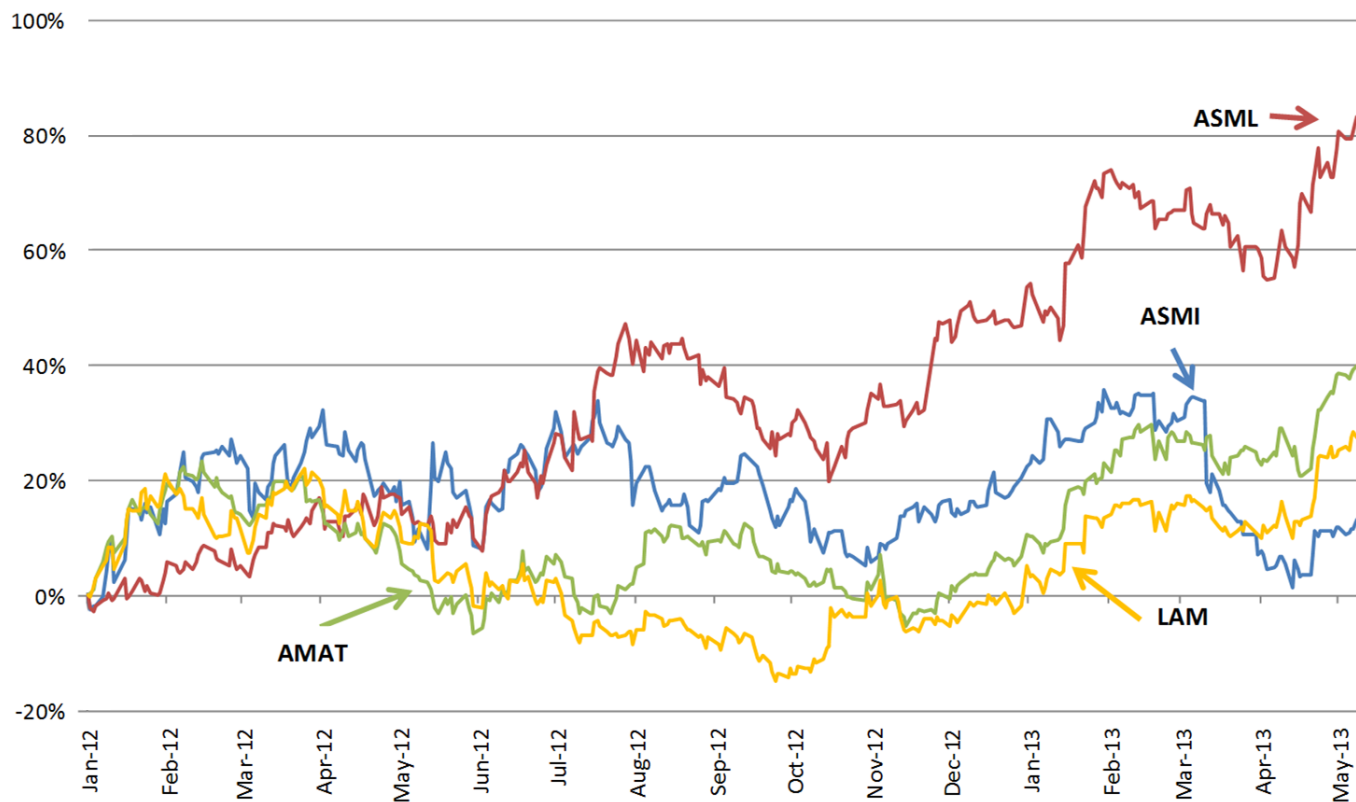
(EUR million)	Dividends received	ASMI shares repurchased	Convertible bonds repurchased	Dividend pay outs	Balance
2007	49.1		-32.9	-5.4	10.8
2008	49.1	-36.5	-27.1		-14.5
2009	21.4		-27.0		-5.6
2010	65.6		-55.8		9.8
2011	87.2			-22.3	64.9
2012	*	-40.6		-27.5	-68.1
TOTAL	272.4	-77.1	-142.8	-55.2	-2.7

* 2012 PT dividend received of 29.5 was not part of commitment

1.5 million shares bought back in 2012

ASMI SHARE PRICE IN 2012

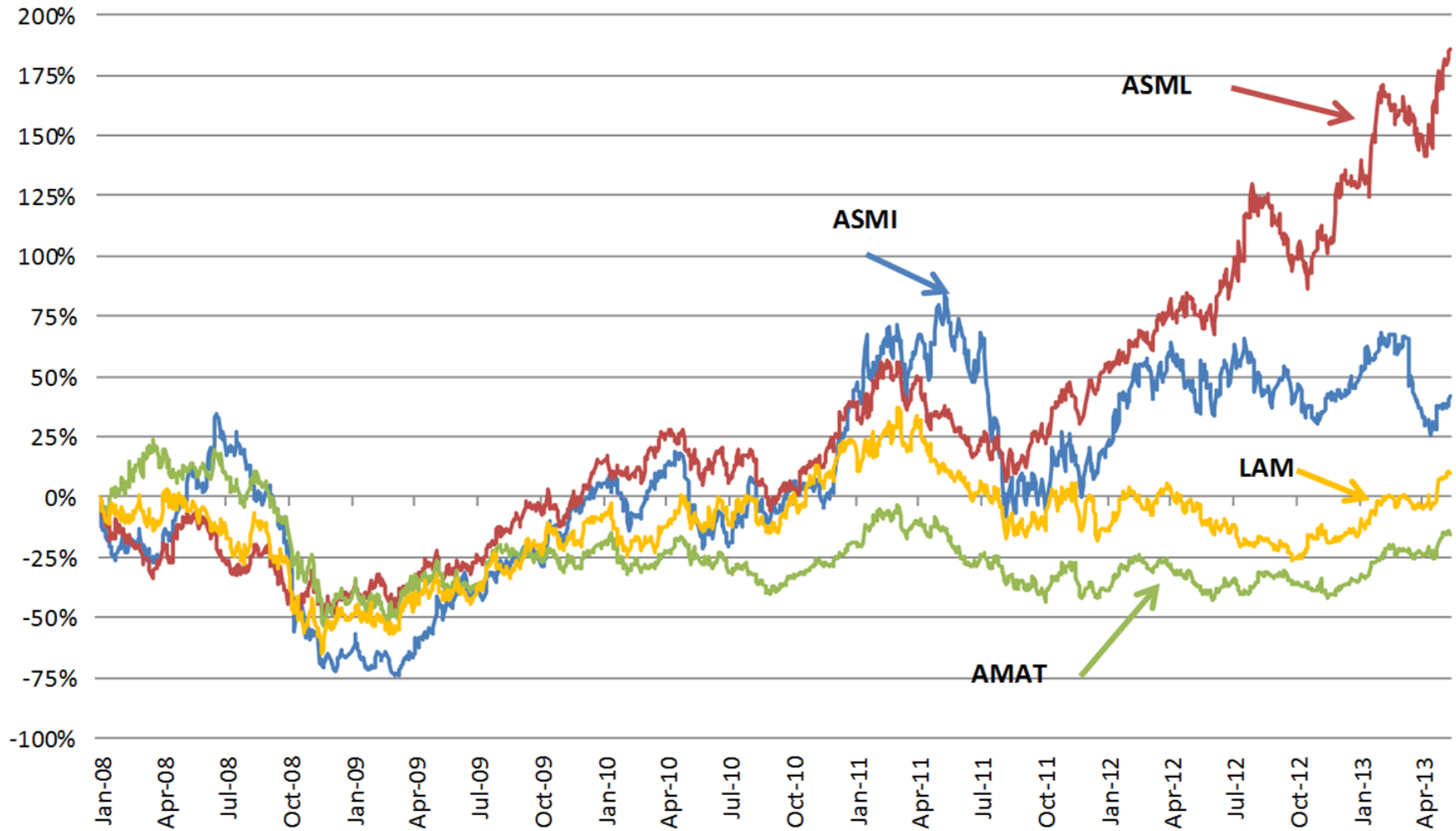
- › ASMI share price increased 20% in 2012, but declined in March'13 following sale stake ASMPT
- › Comparison same sector companies



Source: google.com/finance and Euronext

ASMI SHARE PRICE LAST 5 YEARS

ASMI share price increased 49% (end of 2012) compared to 2008



Source: google.com/finance and Euronext

- › We are committed to the Electronics Industry Citizenship Coalition (EICC) tenets to conduct our business responsibly in all areas of Environment, Health & Safety, Labor, Ethics and Supply Chain.
- › We strive to earn the trust of all stakeholders through responsible and ethical corporate practices.
- › In both our Front-end and Back-end businesses, we pride ourselves in being responsible corporate citizens.

Front-end

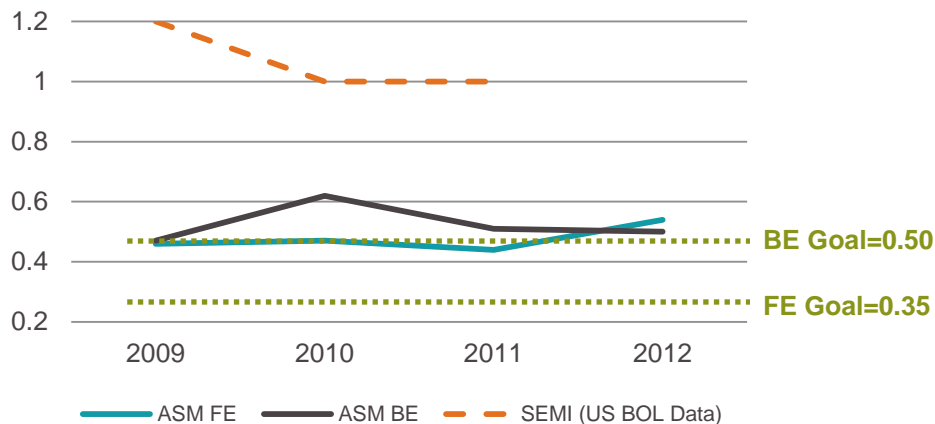
- Sustainability policy published 2/13
- Internal EICC audit all sites completed 1/13
- External EICC re-audit of Singapore site 5/13 successful, zero open findings
- Annual ethics training completed 10/12
- Ethics Scorecard in place 4/13

Back-end

- CSR Policy draft in review, target Q2-13
- 3rd party EICC audit of HK and China complete 7/12, corrective actions underway
- EICC self-assessment done for 5 of 8 facilities, rest complete by Q3-13
- Ethics training all employees annually

Transparency → ASM Internet site - Sustainability

Recordable Case Rate (CY)



Front-end

- › Among benchmark companies
- › Key customer recognition for EHS

Back-end

- › RCR continues to outperform Industry
- › Safety Training top-to-bottom improvement
- › Risk Assessment and risk-focused actions

Front-end

- › Global ISO14001 by 7/13
- › Environmental Scorecard 1/13
- › Carbon Disclosure Project (CDP) participation 5/13

Back-end

- › 5 of 8 facilities ISO14001 certified now
- › Global ISO14001 target by 2016 end
- › Environmental Scorecard in place

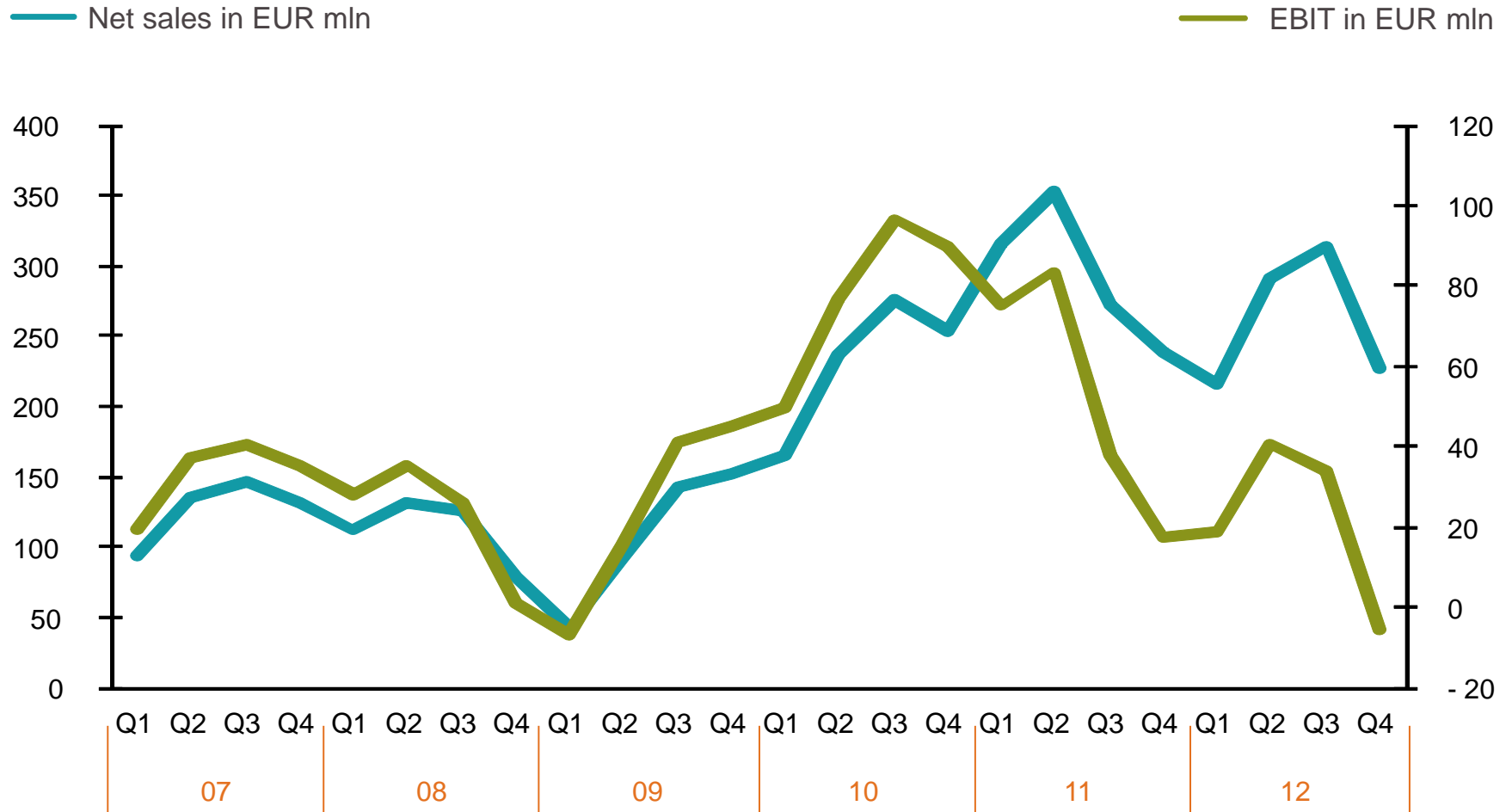
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BACK-END – WHAT HAS CHANGED IN 2012?

- › Assembly & Packaging revenue down 23% compared to 2011
- › Record leadframe revenue, leadframe business profitable
- › SMT improved its market position and profit margin in 2012

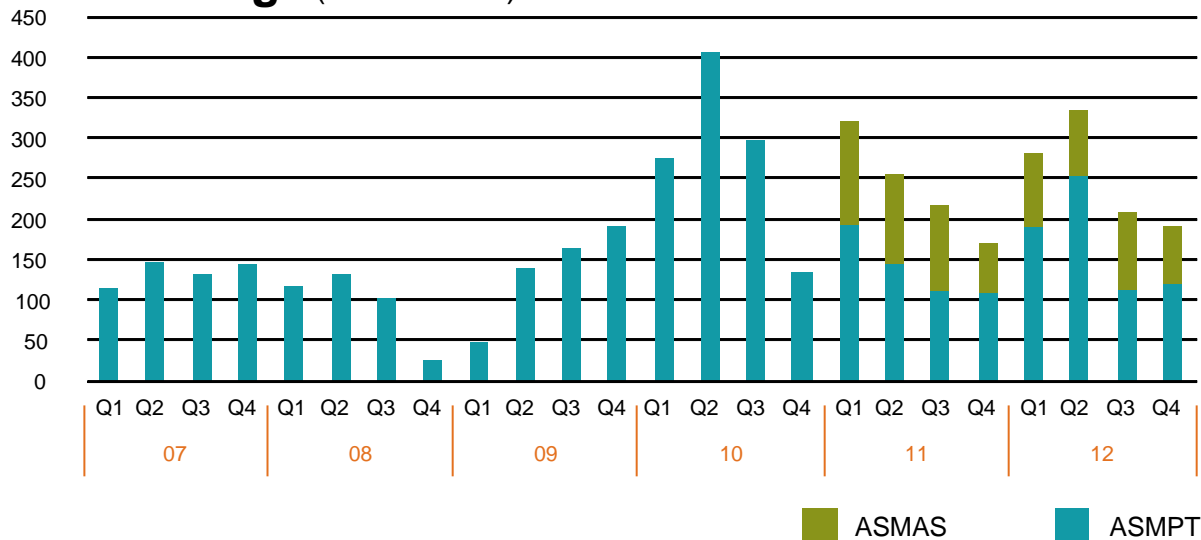
HISTORICAL DEVELOPMENT – BACK-END



SUMMARY 2012 – BACK-END

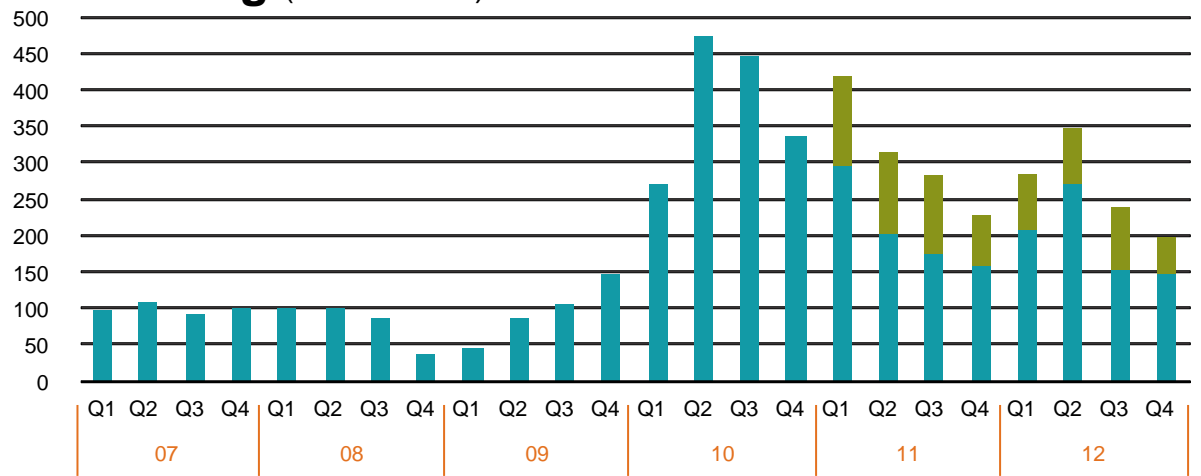
(EUR million)	FULL YEAR 2011	FULL YEAR 2012	Q1 2012	Q2 2012	Q3 2012	Q4 2012
Net sales	1,178.3	1,047.7	216.3	291.4	313.2	226.8
Gross margin	409.8	315.9	65.3	102.0	95.3	53.3
as % of sales	34.8%	30.2%	30.2%	35.0%	30.4%	23.5%
Selling, general and administrative	(115.3)	(137.6)	(26.6)	(38.5)	(37.2)	(35.4)
Research & development	(80.9)	(90.5)	(19.7)	(23.1)	(24.5)	(23.2)
EBIT (EXCL. IMPAIRMENT)	213.7	87.7	19.0	40.5	33.6	(5.3)
as % of sales	18.1%	8.4%	8.8%	13.9%	10.7%	-2.3%
Bookings	971	1,017	282	334	210	191
BOOK-TO-BILL	0.8	1.0	1.3	1.1	0.7	0.8

Bookings (EUR million)



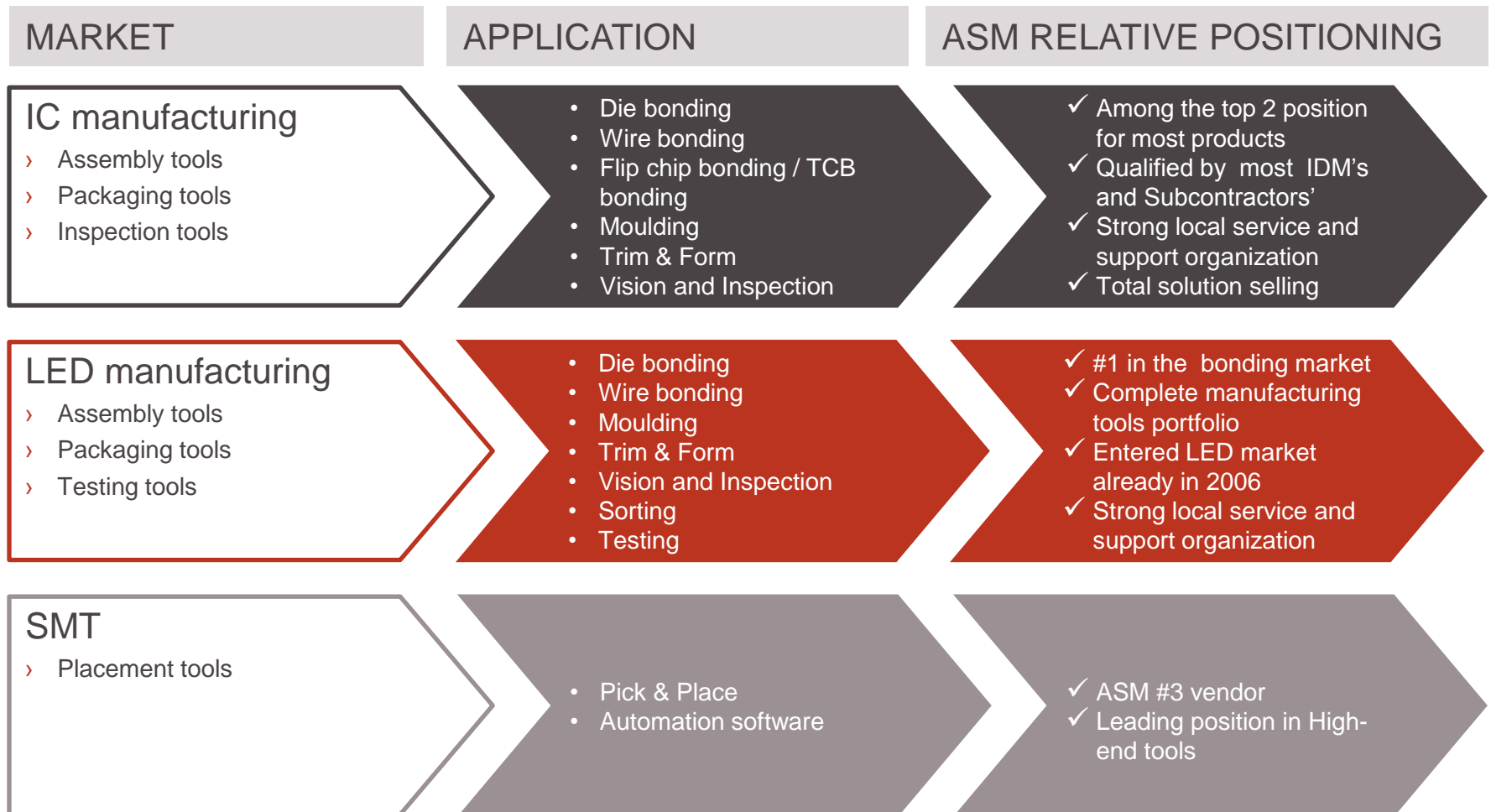
Book-to-Bill ratio in 2012 was 1.0

Backlog (EUR million)



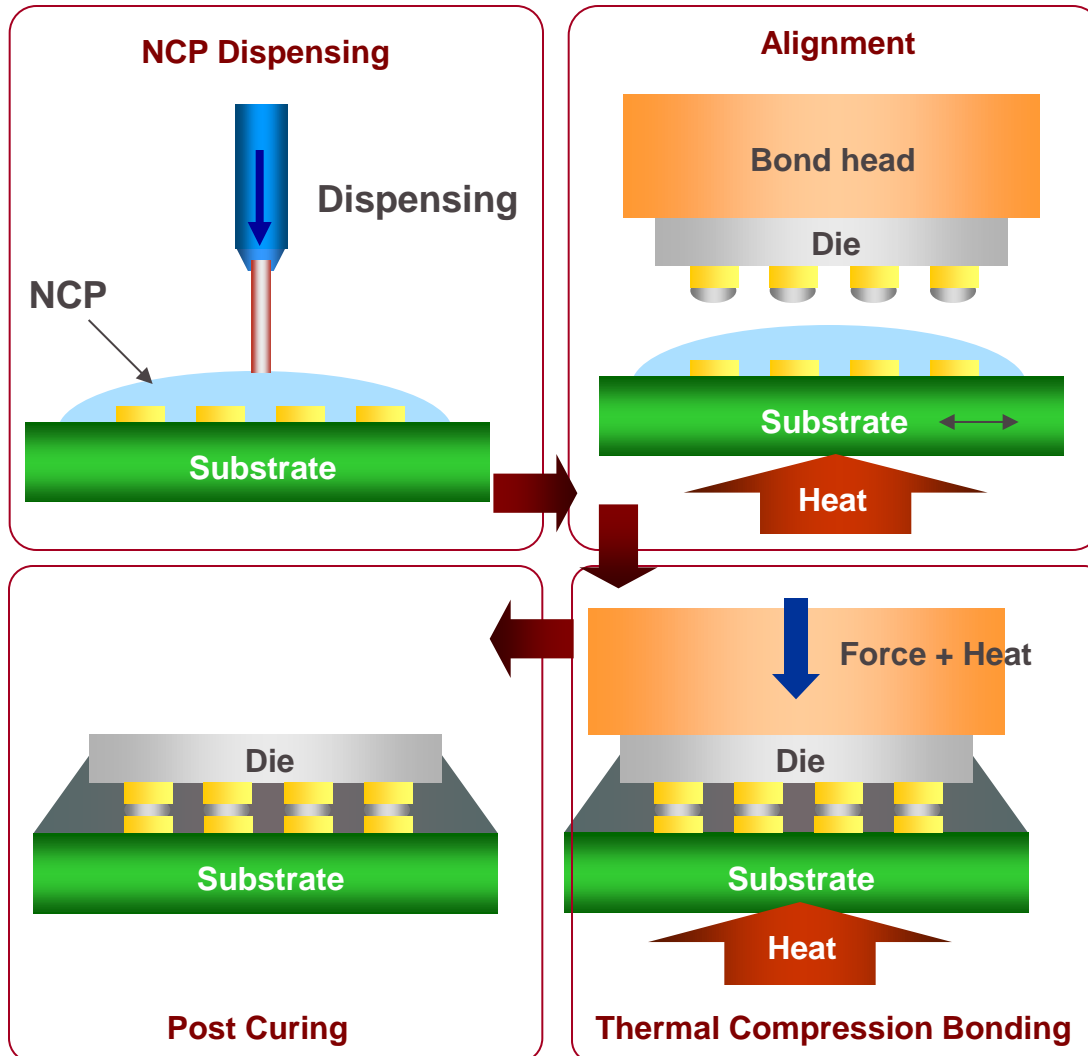
Backlog declined 12% to €198m in 2012

IC manufacturing - LED manufacturing - Surface Mount Technology



BACK-END PRODUCT HIGHLIGHTS

THERMAL COMPRESSION BONDING (TCB) PROCESS



- > Capable to address fine pitch flip chip (Cu pillar) bonding and 2.5D/3D package applications
- > Popularity of mobile devices expected to accelerate adoption of 2.5D/3D packages

Chip Assembly (CA) solution for advanced packages

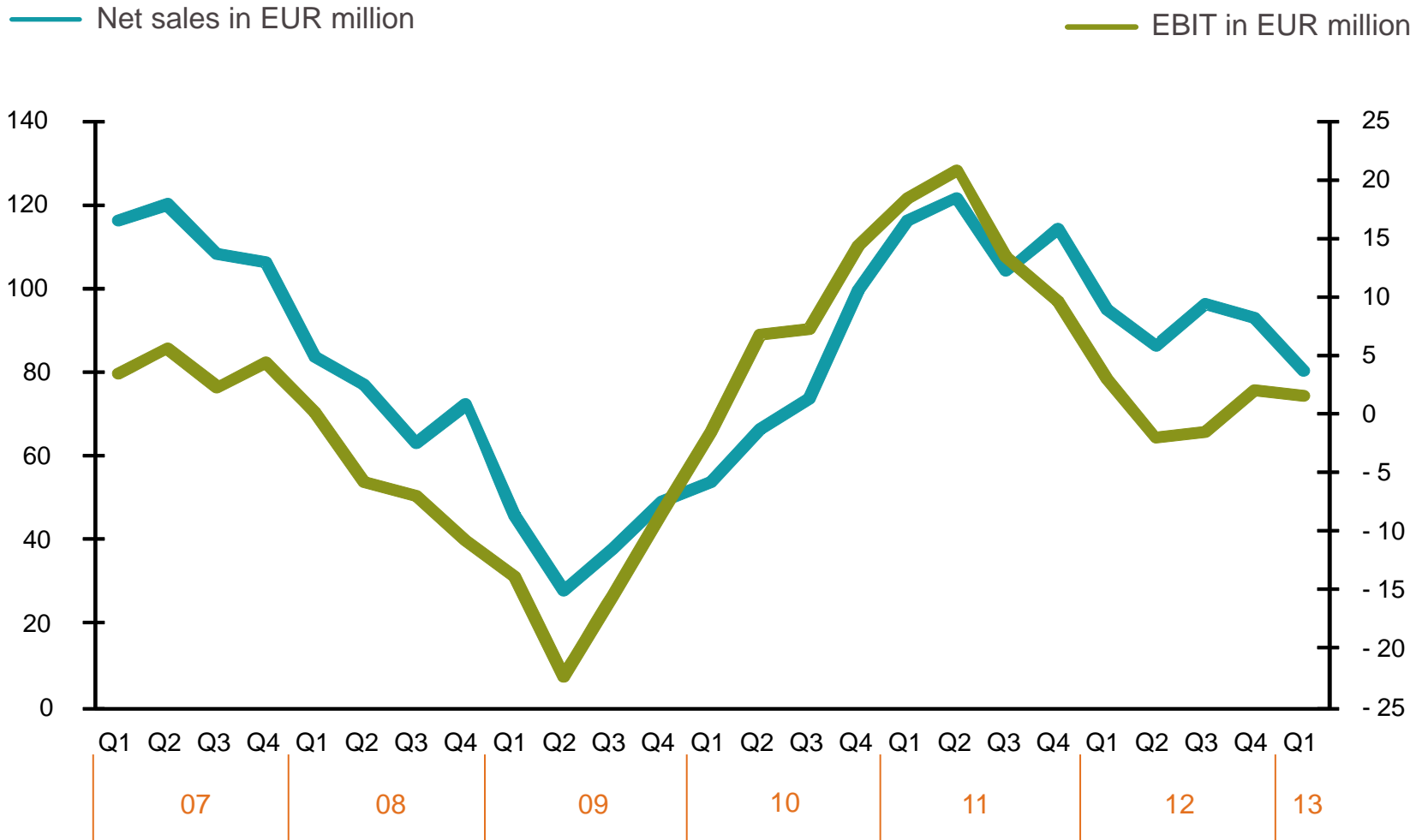


- › Expanding SMT equipment into non-traditional placement market
- › Ideal for WLFO (Wafer Level Fan Out), SiP (System-in-package), LED, Embedded PCB and flip chips
- › Enables the combination of flip-chip and SMT operations in a single pass
- › Supports direct die attach
- › Supports large panel areas
- › Very high production speed and throughput

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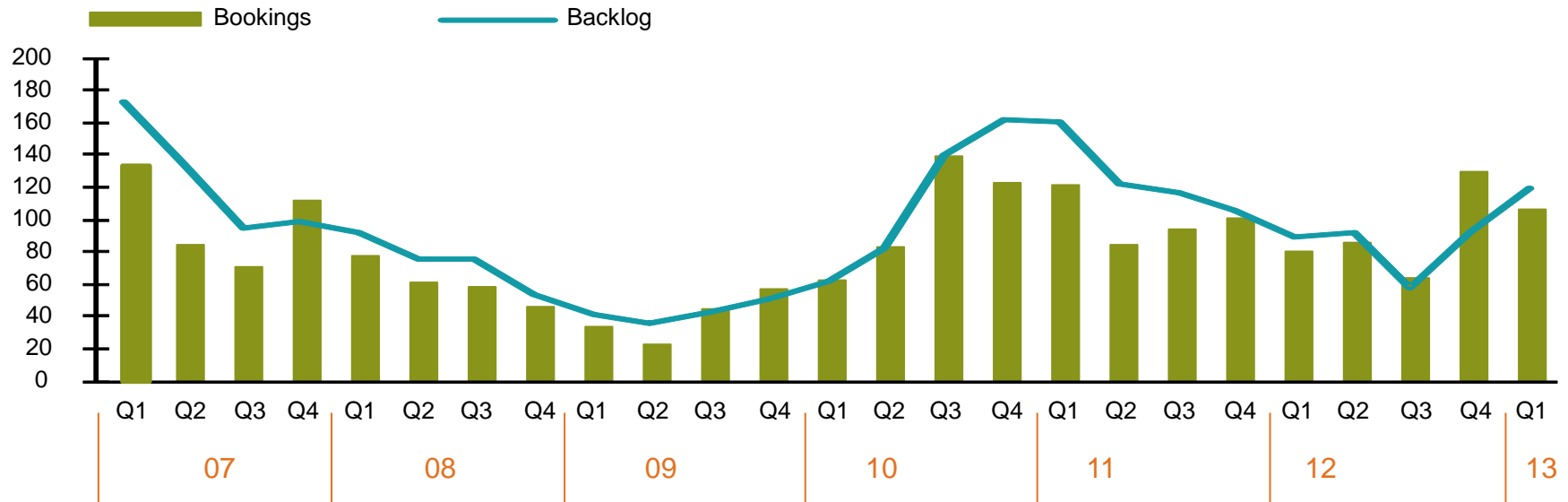
HISTORICAL DEVELOPMENT – FRONT-END



SUMMARY 2012 – FRONT-END

(EUR million)	Full Year 2011	Full Year 2012	Q1 2012	Q2 2012	Q3 2012	Q4 2012	Q1 2013
Net sales	456.1	370.4	94.8	86.5	96.1	93.1	80.0
Gross margin	172.3	124.5	31.3	28.5	30.1	34.6	30.2
as % of sales	37.8%	33.6%	33.0%	32.9%	31.4%	37.1%	37.7%
Selling, general and administrative	(61.2)	(64.4)	(14.6)	(15.4)	(16.3)	(18.2)	(15.3)
Research & development	(48.5)	(58.7)	(13.8)	(15.1)	(15.4)	(14.3)	(13.4)
EBIT (excl. restructuring)	62.6	1.4	2.9	(1.9)	(1.6)	2.1	1.4
as % of sales	13.7%	0.4%	3.0%	-2.2%	-1.7%	2.3%	1.8%
Bookings	398	360	81	86	64	129	106
Book-to-Bill	0.9	1.0	0.8	1.0	0.7	1.4	1.3

Bookings & Backlog – Front-end



Book-to-Bill ratio in 2012 of 1.0

- › Market requirements: 32nm → 22nm → 14nm and beyond
- › Strong IP protected portfolio

PROCESS	APPLICATION	ASM RELATIVE POSITIONING
ALD and PEALD <ul style="list-style-type: none"> › ALD solution (Hafnium oxide) › PEALD Low temp dielectrics 	<ul style="list-style-type: none"> • ALD key for High-k Metal Gate technology • 3D FinFET requires more conformal layers, strength of ALD • SDDP-application of PEALD 	<ul style="list-style-type: none"> ✓ #1 in the served ALD market ✓ Qualified by nearly all Logic & Foundry manufacturers ✓ Strengthening inroads with PEALD
Diffusion Furnace <ul style="list-style-type: none"> › Unique “dual reactor dual boat” design 	<ul style="list-style-type: none"> • Smallest footprint per reactor • Low Cost of Ownership 	<ul style="list-style-type: none"> ✓ Leading IC manufacturers are customers
Epitaxy <ul style="list-style-type: none"> › Epitaxial films for both analog devices as well as NMOS/PMOS 	<ul style="list-style-type: none"> • Thick Epi layers for power devices • Strained Epi films for CMOS 	<ul style="list-style-type: none"> ✓ ASM one of only two top vendors
PECVD <ul style="list-style-type: none"> › Extreme low-k films 	<ul style="list-style-type: none"> • Advanced intermetal dielectric film 	<ul style="list-style-type: none"> ✓ ASM one of only two top vendors in PE-CVD Low-k

- › ALD and PEALD strongly developed further traction in 2012
- › Growing share of wallet with top clients
- › Two new high productivity platforms introduced in 2012
- › Gross margin improvement focus
 - Inefficiency issues solved
 - Several cost measures in implementation
 - Further savings opportunities identified in supply chain

Two new high productivity platforms



Intrepid™ XP

Epitaxy

High productivity XP cluster with 4 Epi reactors

Dragon® XP8

PECVD

Eagle® XP8

PEALD

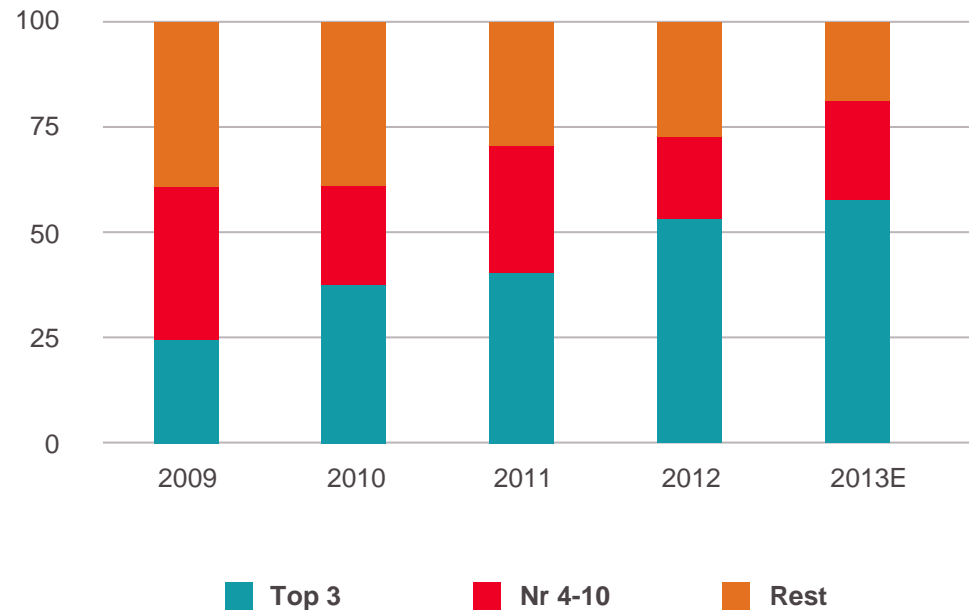
High throughput, low CoO single wafer deposition tool

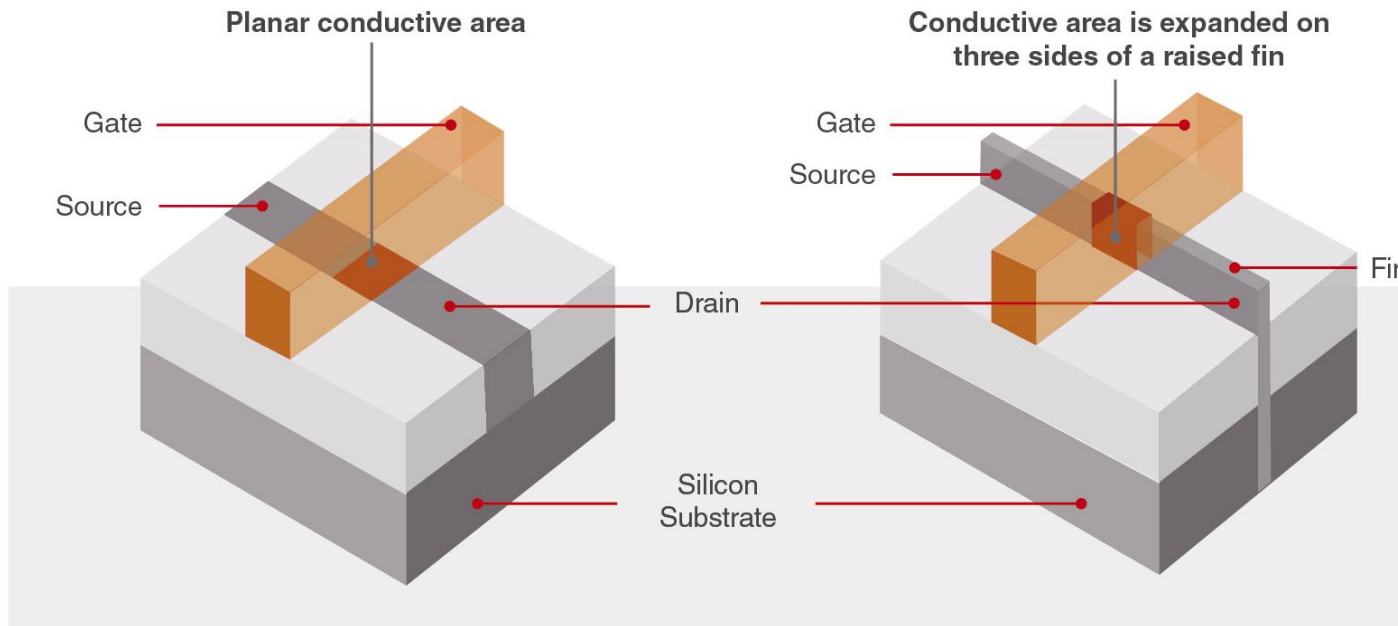


Key Developments:

- › Diversification of customer base from Logic to Memory and Foundries
- › Weight of Asia growing
- › Wider adoption number of top capex customers

Customer Revenue (%)





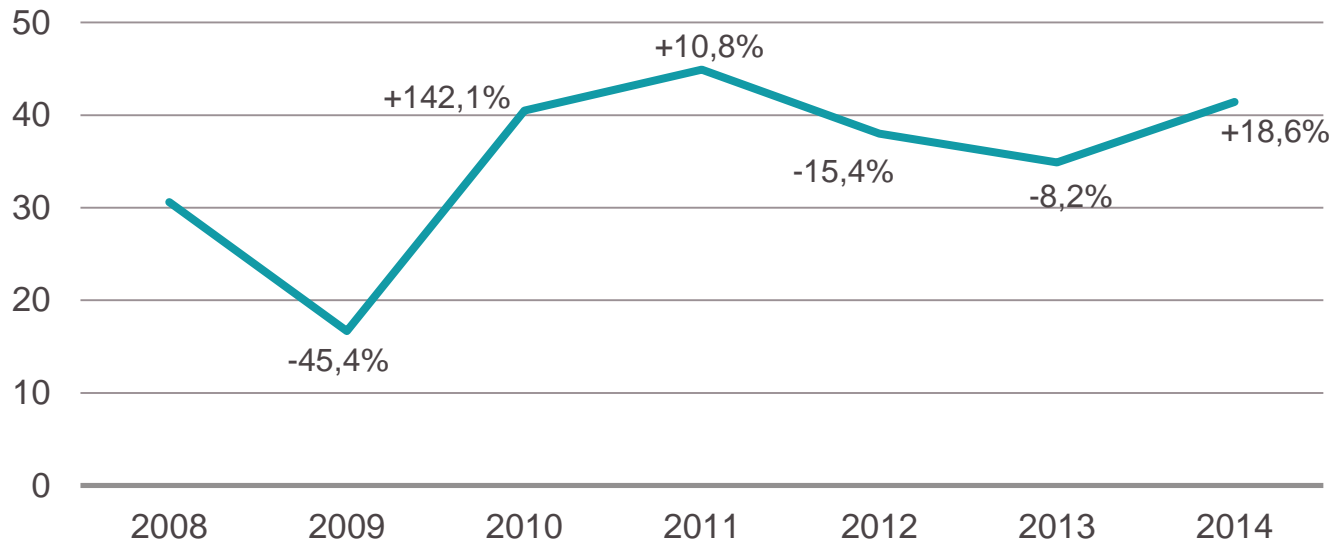
- › Established a leading position in ALD technology, since start in 1999
- › Shift from Planar Logic to 3D FinFET will require more ALD/PEALD
- › PEALD offered on high productivity platform
- › ASMI is one of the two leading suppliers of PECVD Low-k films
- › In the EPI market ASMI is one of only two global suppliers

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Semi capital equipment outlook

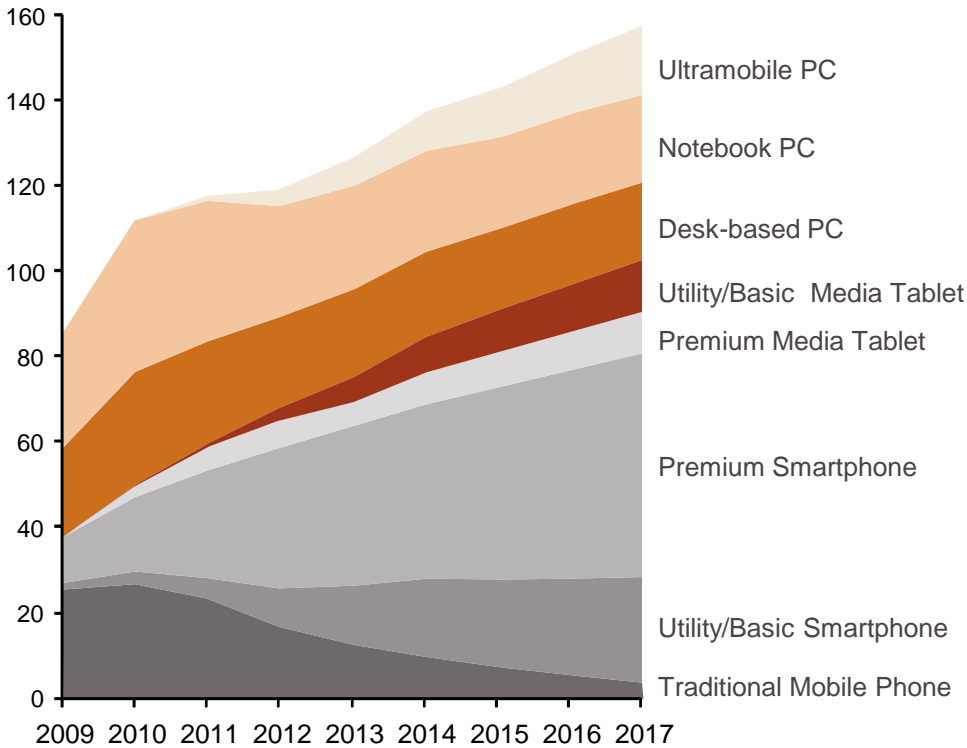
(USD billion)



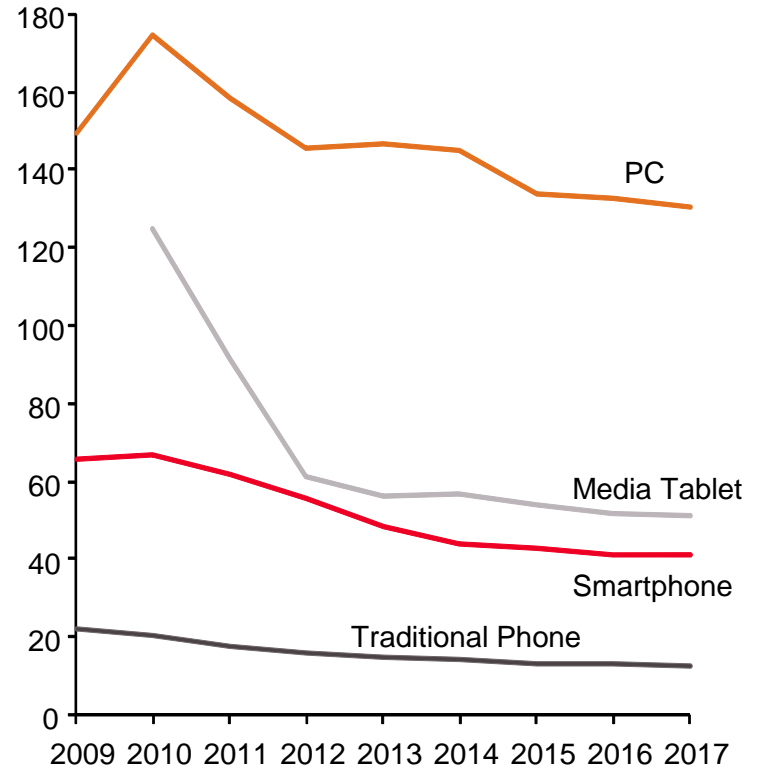
Market predicted to be down in 2013 by approximately 8% and to grow in 2014

Source: Gartner, March 2013

Semiconductor Sales¹ (\$B)



Semiconductor Dollars Per Unit¹ (\$)

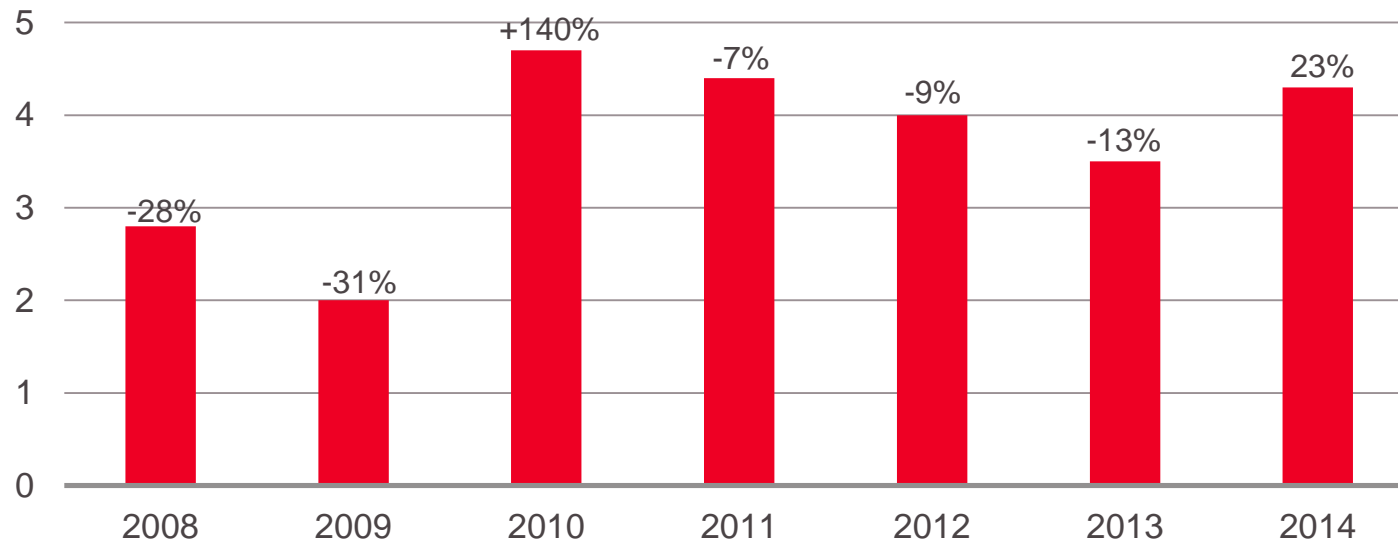


1 - excludes SSD / ODD / RDD / Ethernet / graphics cards

Source: Gartner (March 2013)

Assembly & Packaging equipment

(USD billion)

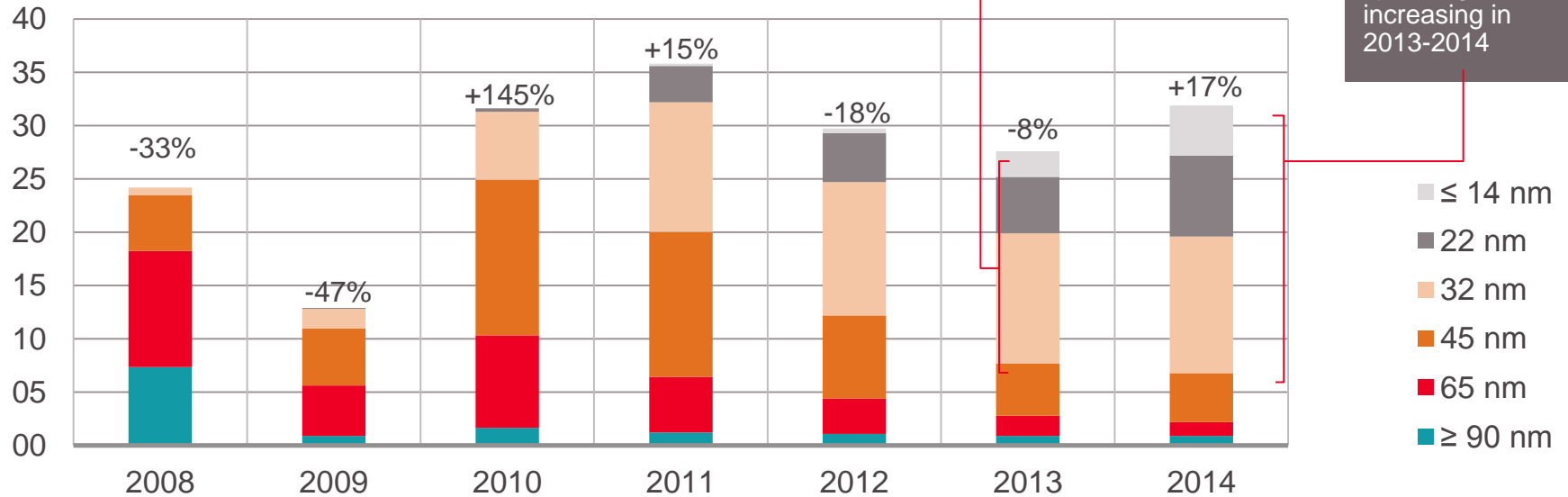


Assembly & Packaging equipment spending is expected to decline in 2013, and to rebound in 2014

Source: Gartner, March 2013

Wafer Fab Equipment Forecast by technology node

(USD billion)



Market Forecast shows growth in advanced technology nodes

Source: Gartner, March 2013

› **Based upon the current backlog and our current visibility:**

- Following the healthy book to bill ratios in Q4 2012 and Q1 2013 our Front-end operations are expected to show a strong double digit sales increase in Q2 compared to Q1.

We also expect a double digit increase of our order-intake in Q2 compared to Q1.

- › **Front-end revenue declined 19% compared to 2011**
- › **Back-end revenue declined 11% compared to 2011**
- › **ALD and PEALD strongly developed further traction in 2012**
- › **Continued focus on Front-end Gross Margin improvement**
- › **Company believes to be well positioned to benefit from the semi industry end product growth drivers in 2013-2017**
- › **Technology shift in the industry will require more ALD/PEALD**
- › **Front-end equipment market believed to turn around in 2013 versus weak 2012**

